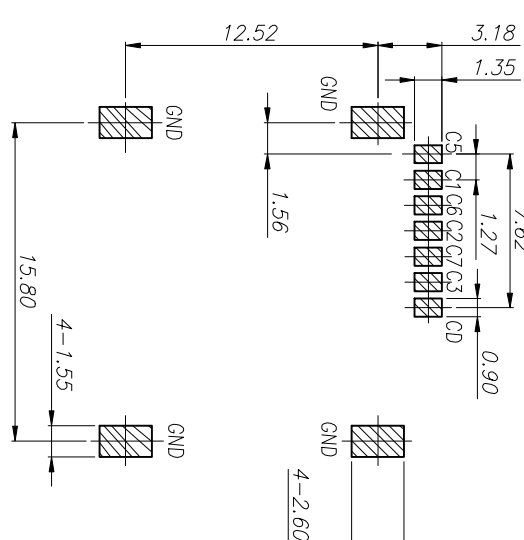
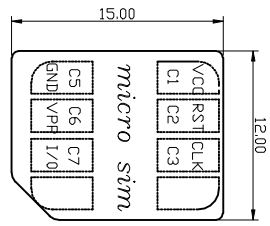
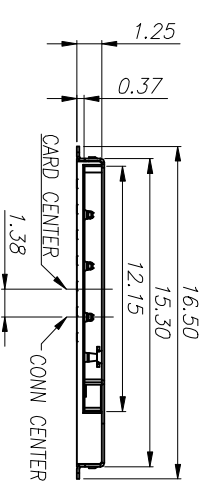
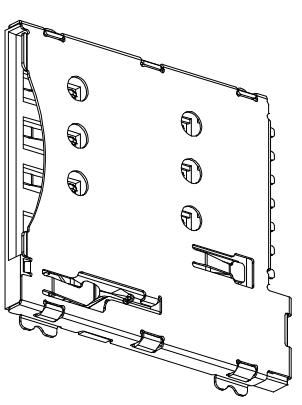
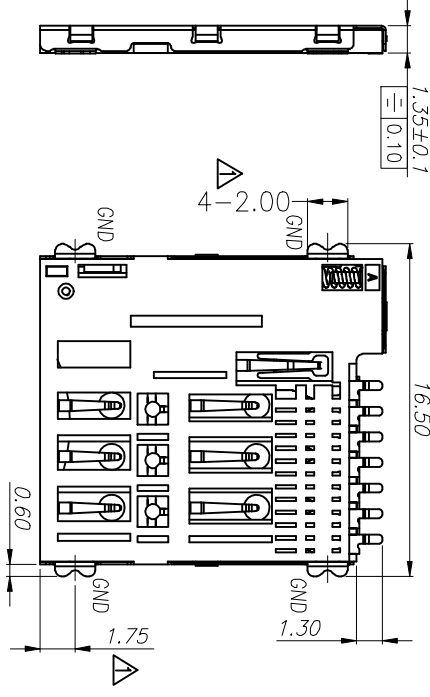
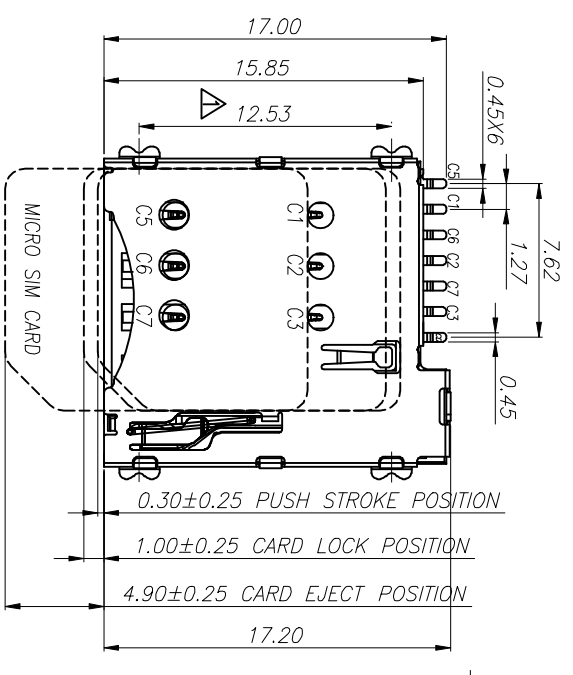


REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A		NEW RELEASE	20140903	ven		changyong
A1		更改外形尺寸和公差	20151022	ven		changyong



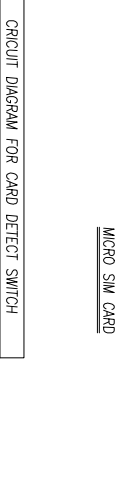
SIM pin Assignment	PIN#	Name
	C1	VCC
	C2	RST
	C3	CLK
	C5	GND
	C6	VPP
	C7	I/O

NOTES:

MATERIAL:
 Insulator: High Temperature Thermoplastic, UL 94V-0
 Cores: Copper Alloy
 Shell: STAINLESS

PLATING:
 TERMINAL:
 CONTACT AREA: GOLD FLAME
 SOLDER AREA: WATER TIN PLATING
 UNDER PLATE: NICKEL
 SILL: NICKEL OVER ALL
 SOLDER AREA: GOLD FLAME

Electrical:
 Current Rating : 0.5A, max.
 Voltage Rating : 50V DC MAX
 Ambient Temperature Range : -20° C ~ 65° C
 Storage Temperature Range : -40° C ~ 100° C
 Initial Humidity Range : 5% ~ 95% R.H. max.
 Contact Resistance: 10mΩ max.
 Insulation Resistance: 100MΩ min. @ 50% RH
 Dielectric Withstanding Voltage: 500V AC
 Insulating Voltage: 500V Insulation
 Temperature: 20V C ±5°



CIRCUIT TRACE KEEP OUT AREA
 SMT SOLDER AREA
 THERE SHOULD NOT BE ANY CIRCUITRIES
 IN THE LAYOUT SPACE OF THE PRODUCTS.
 RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

MILLIMETERS	INCH
X ± 2	X ±
X ± 0.30	XX ±
XX ± 0.25	XXX ±
XXX ± 0.15	XXXX ±

UNITS	MM
MATL	SEE NOTES
FINISH	SEE NOTES
APPD:	WGY
CHKD:	
DR:	

深圳市迈睿康科技有限公司

PART NUMBER: MICRO-SIM 4-PIN/5V/1P/50 7PIN 1.38

TITLE: MKR-SIM05-135-0012

DWG NO.: MKR-SIM05-135-0012

QTY	SEE NOTES	SCALE	SHEET	REV.
		1:1	1/2	A1